



Material Content Data Sheet



Sales Product Name		BFP 720F H6327		Issued		27. September 2017		
MA#		MA000895790						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		371	
	noble metal	gold	7440-57-5	0.003	0.14		1439	
	inorganic material	silicon	7440-21-3	0.023	1.25	1.43	12543	14353
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.25	39.42	392528	394184
wire	noble metal	gold	7440-57-5	0.006	0.34	0.34	3416	3416
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5134	
	plastics	epoxy resin	-	0.207	11.04		110386	
	inorganic material	silicondioxide	60676-86-0	0.745	39.80	51.35	397903	513423
leadfinish	non noble metal	tin	7440-31-5	0.050	2.65	2.65	26494	26494
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48130	48130
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com